

REMARKS/ARGUMENTS

Claims 1, 3, 4, 8, and 9 are pending in this application. Claims 13-15 have been cancelled. In view of this Amendment reexamination and reconsideration are respectfully requested.

The Examiner objected to claim 14. This claim has been amended as suggested by the Examiner.

The Examiner rejected claims 8 and 13 under 35 U.S.C. § 102(a) as being unpatentable over Nakamura (5,986,333). Applicant has further amended claim 8 to overcome this rejection. Applicant traverses the Examiner's finding of anticipation and believes the cited art does not teach or suggest the claimed invention as amended. The die pads in Nakamura have a slit at the corner so the corner edge is not under the die pad. In contrast, the amended claim focuses on the embodiment shown in Figure 6 where the die pad has larger openings at the corners. Also, in contrast to Nakamura, the die pad area is significantly reduced with the corner cutouts in the claimed invention instead of the slits.

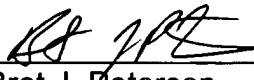
The Examiner rejected claims 1, 3, and 4 under 35 U.S.C. § 103(a) as being unpatentable over Hollingsworth et al (5,521,428). Applicant has further amended claim 8 to overcome this rejection. Applicant traverses the Examiner's finding of anticipation and believes the cited art does not teach or suggest the claimed invention as amended.

In Hollingsworth, the die pad support regions are raised structures on the die pad. The chip does not lie on the die pad, but makes contact with these raised

structures. It is not clear that these structures would give the same benefits as the isolated die pad portions as claimed herein.

In the claimed invention, the die pad portions are isolated portions of the die pad and in contact with the chip. This structure is likely to provide benefits over the Hollingsworth structure since it has significantly different expansion and stress characteristics.

Respectfully submitted,
Texas Instruments Incorporated

By 
Bret J. Petersen
Reg. No. 37,417
Tel.: (972) 917-5339